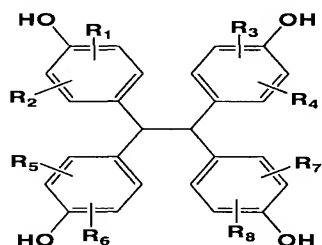


ABSTRACT

Disclosed is a photosensitive resin composition with excellent photosensitivity whose cured product is excellent in adhesiveness, pencil hardness, solvent resistance, acid resistance, heat resistance, gold plating resistance and the like. Also disclosed is such a cured product. Specifically disclosed is a photosensitive resin composition containing a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C) and a curing agent (D) wherein the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than 80% of a tetraphenylethane derivative represented by the following formula (1).



(1)

[In the formula, R₁ to R₈ independently represents a hydrogen

atom, a C₁-C₄ alkyl group or a halogen atom.]